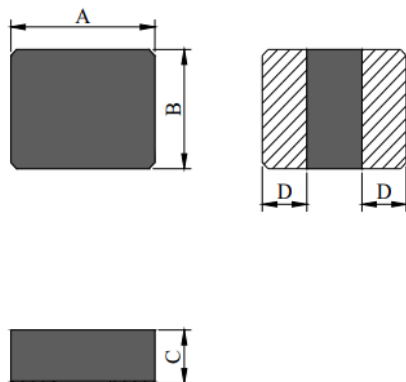


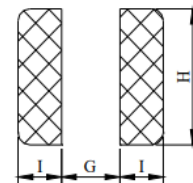
MMD252012-DCseries



SHAPE AND DIMENSIONS (mm)



RECOMMENDED PATTERN (mm)



Type	A	B	C	D	G	H	I
MMD252012	2.5±0.2	2.0±0.2	1.2Max.	0.9 ref.	1.0 ref.	2.3 ref.	0.9 ref.

APPLICATION

Laptop, Smartphone, LCD panel,
Bluetooth and other electronic devices

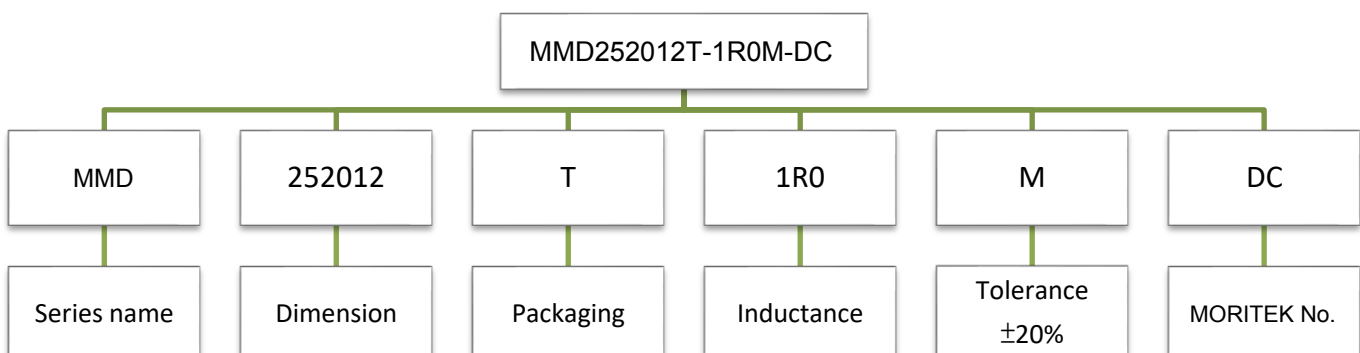
RATING

Operating Temperature : -55°C ~ +125°C
Storage Temperature : Under 40°C, Humidity < 75%

MATERIAL LIST

- a. Core : Alloy powder
- b. Wire : Enameled copper wire
- c. Terminal : Cu / Ni / Sn

PRODUCT IDENTIFICATION (ex.)



ELECTRICAL CHARACTERISTICS

Part No.	Inductance (uH)	Inductance tolerance	Test Frequency	DC Resistance (Ω)		Saturation current Isat(mA)		Temperature rise current Irms(mA)	
				Typ.	Max.	Typ.	Max.	Typ.	Max.
MMD252012T-R24M-DC	0.24	±20%	1MHz	0.010	0.015	9300	8800	8000	7500
MMD252012T-R33M-DC	0.33	±20%	1MHz	0.011	0.017	8300	7800	6800	6400
MMD252012T-R47M-DC	0.47	±20%	1MHz	0.013	0.019	7500	7000	6500	6000
MMD252012T-R68M-DC	0.68	±20%	1MHz	0.017	0.023	6500	6000	6300	5500
MMD252012T-1R0M-DC	1.0	±20%	1MHz	0.035	0.042	5600	5000	4000	3600
MMD252012T-1R5M-DC	1.5	±20%	1MHz	0.044	0.050	4500	4100	3700	3200
MMD252012T-2R2M-DC	2.2	±20%	1MHz	0.055	0.065	3800	3300	3000	2700
MMD252012T-3R3M-DC	3.3	±20%	1MHz	0.080	0.097	3000	2700	2300	1800
MMD252012T-4R7M-DC	4.7	±20%	1MHz	0.150	0.170	2400	2100	1800	1500
MMD252012T-6R8M-DC	6.8	±20%	1MHz	0.245	0.270	2000	1700	1600	1400
MMD252012T-100M-DC	10	±20%	1MHz	0.330	0.400	1600	1450	1200	1050

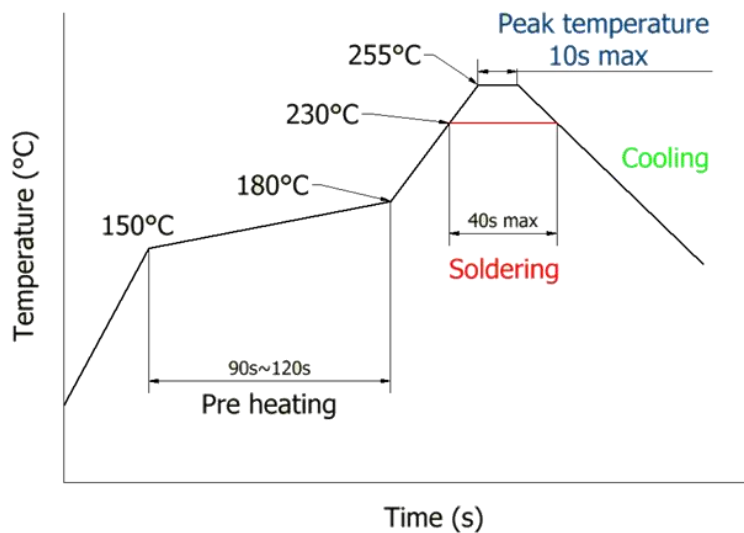
Note:

All test data is referenced to 25°C ambient

Isat base on $\Delta L / L0A=30$

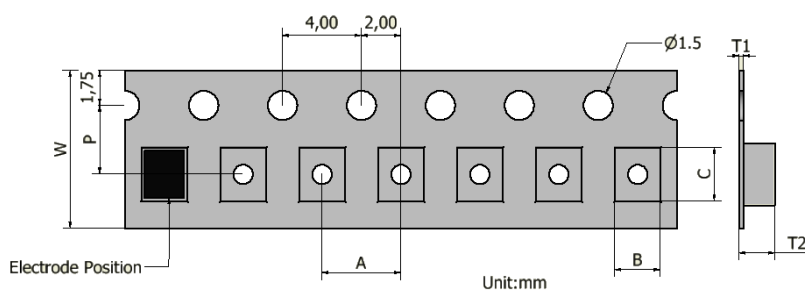
Irms base on Temp. rise 40

RECOMMENDED SOLDERING CONDITIONS



PACKAGE

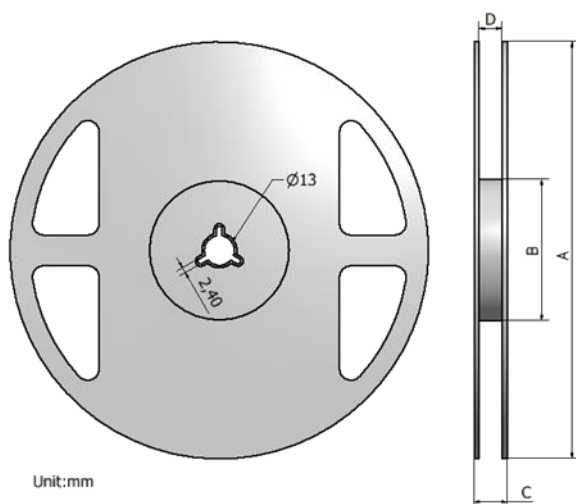
(1) Taping specifications



Type	W	P	A	B	C	T1	T2
MMD252012	8	3.5	4.0	2.3	2.7	0.23	1.2

(2) Reel specifications

Label



Molding Power Inductors
MMD252012T-□□□M-DC
3,000 PCS
Lot No. _____
MORITEK TECHNICAL CO., LTD.

Type	A	B	C	D	Q'ty/Reel
MMD252012	178	60	12	9	3000